

FDMA3023PZ

Dual P-Channel PowerTrench® MOSFET

-30 V, -2.9 A, 90 mΩ

Features

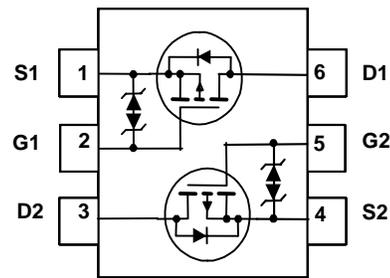
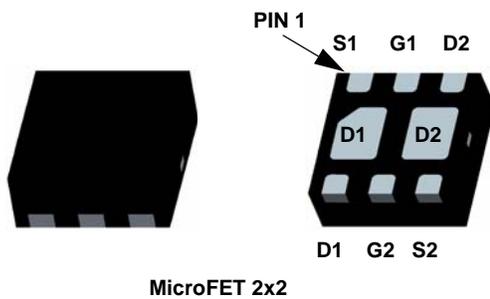
- Max $r_{DS(on)}$ = 90 mΩ at $V_{GS} = -4.5$ V, $I_D = -2.9$ A
- Max $r_{DS(on)}$ = 130 mΩ at $V_{GS} = -2.5$ V, $I_D = -2.6$ A
- Max $r_{DS(on)}$ = 170 mΩ at $V_{GS} = -1.8$ V, $I_D = -1.7$ A
- Max $r_{DS(on)}$ = 240 mΩ at $V_{GS} = -1.5$ V, $I_D = -1.0$ A
- Low profile - 0.8 mm maximum - in the new package MicroFET 2x2 mm
- HBM ESD protection level > 2 kV (Note 3)
- RoHS Compliant
- Free from halogenated compounds and antimony oxides



General Description

This device is designed specifically as a single package solution for the battery charge switch in cellular handset and other ultra-portable applications. It features two independent P-Channel MOSFETs with low on-state resistance for minimum conduction losses. When connected in the typical common source configuration, bi-directional current flow is possible.

The MicroFET 2X2 package offers exceptional thermal performance for its physical size and is well suited to linear mode applications.



MOSFET Maximum Ratings $T_A = 25$ °C unless otherwise noted

| Symbol | Parameter | Ratings | Units |
|----------------|--|-------------|-------|
| V_{DS} | Drain to Source Voltage | -30 | V |
| V_{GS} | Gate to Source Voltage | ±8 | V |
| I_D | Drain Current -Continuous (Note 1a) | -2.9 | A |
| | -Pulsed | -6 | |
| P_D | Power Dissipation (Note 1a) | 1.4 | W |
| | Power Dissipation (Note 1b) | 0.7 | |
| T_J, T_{STG} | Operating and Storage Junction Temperature Range | -55 to +150 | °C |

Thermal Characteristics

| | | | |
|-----------------|--|-----|------|
| $R_{\theta JA}$ | Thermal Resistance for Single Operation, Junction to Ambient (Note 1a) | 86 | °C/W |
| $R_{\theta JA}$ | Thermal Resistance for Single Operation, Junction to Ambient (Note 1b) | 173 | |
| $R_{\theta JA}$ | Thermal Resistance for Dual Operation, Junction to Ambient (Note 1c) | 69 | |
| $R_{\theta JA}$ | Thermal Resistance for Dual Operation, Junction to Ambient (Note 1d) | 151 | |

Package Marking and Ordering Information

| Device Marking | Device | Package | Reel Size | Tape Width | Quantity |
|----------------|------------|--------------|-----------|------------|------------|
| 323 | FDMA3023PZ | MicroFET 2X2 | 7" | 8 mm | 3000 units |

Electrical Characteristics $T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Units |
|--------|-----------|-----------------|-----|-----|-----|-------|
|--------|-----------|-----------------|-----|-----|-----|-------|

Off Characteristics

| | | | | | | |
|--------------------------------------|---|--|-----|-----|-----------|----------------------|
| BV_{DSS} | Drain to Source Breakdown Voltage | $I_D = -250\text{ }\mu\text{A}$, $V_{GS} = 0\text{ V}$ | -30 | | | V |
| $\frac{\Delta BV_{DSS}}{\Delta T_J}$ | Breakdown Voltage Temperature Coefficient | $I_D = -250\text{ }\mu\text{A}$, referenced to $25\text{ }^\circ\text{C}$ | | -24 | | mV/ $^\circ\text{C}$ |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS} = -24\text{ V}$, $V_{GS} = 0\text{ V}$ | | | -1 | μA |
| I_{GSS} | Gate to Source Leakage Current | $V_{GS} = \pm 8\text{ V}$, $V_{DS} = 0\text{ V}$ | | | ± 100 | nA |

On Characteristics

| | | | | | | |
|--|--|--|------|------|------|----------------------|
| $V_{GS(th)}$ | Gate to Source Threshold Voltage | $V_{GS} = V_{DS}$, $I_D = -250\text{ }\mu\text{A}$ | -0.4 | -0.6 | -1.0 | V |
| $\frac{\Delta V_{GS(th)}}{\Delta T_J}$ | Gate to Source Threshold Voltage Temperature Coefficient | $I_D = -250\text{ }\mu\text{A}$, referenced to $25\text{ }^\circ\text{C}$ | | 3 | | mV/ $^\circ\text{C}$ |
| $r_{DS(on)}$ | Static Drain to Source On Resistance | $V_{GS} = -4.5\text{ V}$, $I_D = -2.9\text{ A}$ | | 71 | 90 | m Ω |
| | | $V_{GS} = -2.5\text{ V}$, $I_D = -2.6\text{ A}$ | | 97 | 130 | |
| | | $V_{GS} = -1.8\text{ V}$, $I_D = -1.7\text{ A}$ | | 122 | 170 | |
| | | $V_{GS} = -1.5\text{ V}$, $I_D = -1.0\text{ A}$ | | 151 | 240 | |
| | | $V_{GS} = -4.5\text{ V}$, $I_D = -2.9\text{ A}$, $T_J = 125\text{ }^\circ\text{C}$ | | 110 | 140 | |
| g_{FS} | Forward Transconductance | $V_{DS} = -5\text{ V}$, $I_D = -2.9\text{ A}$ | | 10 | | S |

Dynamic Characteristics

| | | | | | | |
|-----------|------------------------------|---|--|-----|-----|----|
| C_{iss} | Input Capacitance | $V_{DS} = -15\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 1\text{ MHz}$ | | 400 | 530 | pF |
| C_{oss} | Output Capacitance | | | 55 | 70 | pF |
| C_{rss} | Reverse Transfer Capacitance | | | 45 | 65 | pF |

Switching Characteristics

| | | | | | | |
|--------------|-------------------------------|---|--|-----|-----|----|
| $t_{d(on)}$ | Turn-On Delay Time | $V_{DD} = -15\text{ V}$, $I_D = -1.0\text{ A}$, $V_{GS} = -4.5\text{ V}$, $R_{GEN} = 6\text{ }\Omega$ | | 5 | 10 | ns |
| t_r | Rise Time | | | 4 | 10 | ns |
| $t_{d(off)}$ | Turn-Off Delay Time | | | 62 | 100 | ns |
| t_f | Fall Time | | | 18 | 33 | ns |
| $Q_{g(TOT)}$ | Total Gate Charge | | | 7.9 | 11 | nC |
| Q_{gs} | Gate to Source Charge | $V_{DD} = -15\text{ V}$, $I_D = -2.9\text{ A}$ | | 0.9 | | nC |
| Q_{gd} | Gate to Drain "Miller" Charge | $V_{GS} = -4.5\text{ V}$ | | 1.9 | | nC |

Drain-Source Diode Characteristics

| | | | | | | |
|----------|---|--|--|------|------|----|
| I_S | Maximum Continuous Drain-Source Diode Forward Current | | | | -1.1 | A |
| V_{SD} | Source to Drain Diode Forward Voltage | $V_{GS} = 0\text{ V}$, $I_S = -1.1\text{ A}$ (Note 2) | | -0.8 | -1.2 | V |
| t_{rr} | Reverse Recovery Time | $I_F = -2.9\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$ | | 18 | 33 | ns |
| Q_{rr} | Reverse Recovery Charge | | | 6.6 | 13 | nC |

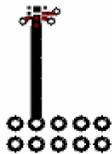
Notes:

1. $R_{\theta JA}$ is determined with the device mounted on a 1 in² oz. copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design.

- (a) $R_{\theta JA} = 86$ °C/W when mounted on a 1 in² pad of 2 oz copper, 1.5 " x 1.5 " x 0.062 " thick PCB. For single operation.
- (b) $R_{\theta JA} = 173$ °C/W when mounted on a minimum pad of 2 oz copper. For single operation.
- (c) $R_{\theta JA} = 69$ °C/W when mounted on a 1 in² pad of 2 oz copper, 1.5 " x 1.5 " x 0.062 " thick PCB. For dual operation.
- (d) $R_{\theta JA} = 151$ °C/W when mounted on a minimum pad of 2 oz copper. For dual operation.



a) 86 °C/W when mounted on a 1 in² pad of 2 oz copper.



b) 173 °C/W when mounted on a minimum pad of 2 oz copper.



c) 69 °C/W when mounted on a 1 in² pad of 2 oz copper.



d) 151 °C/W when mounted on a minimum pad of 2 oz copper.

2. Pulse Test : Pulse Width < 300 us, Duty Cycle < 2.0%

3. The diode connected between the gate and source serves only as protection against ESD. No gate overvoltage rating is implied.

Typical Characteristics $T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted

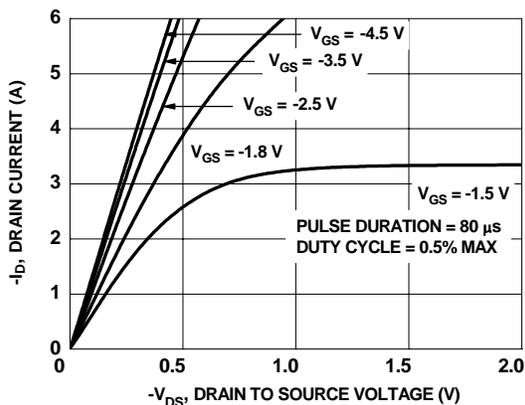


Figure 1. On Region Characteristics

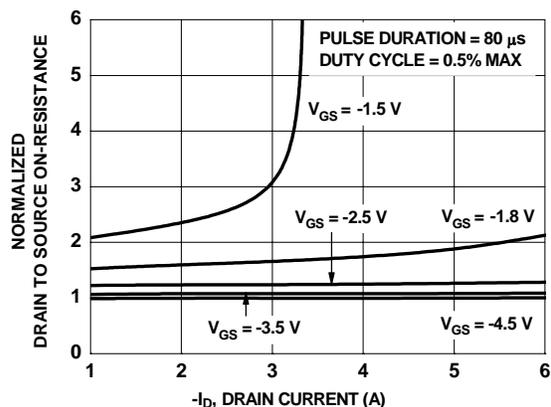


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

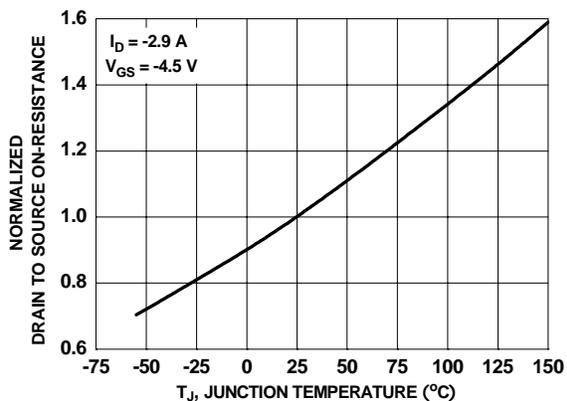


Figure 3. Normalized On Resistance vs Junction Temperature

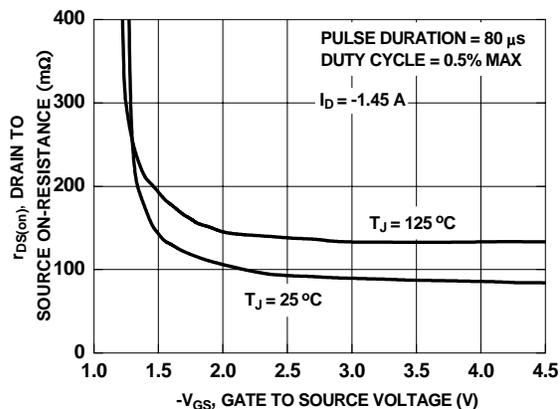


Figure 4. On-Resistance vs Gate to Source Voltage

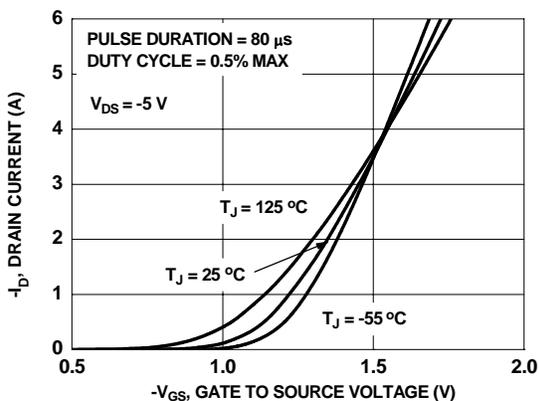


Figure 5. Transfer Characteristics

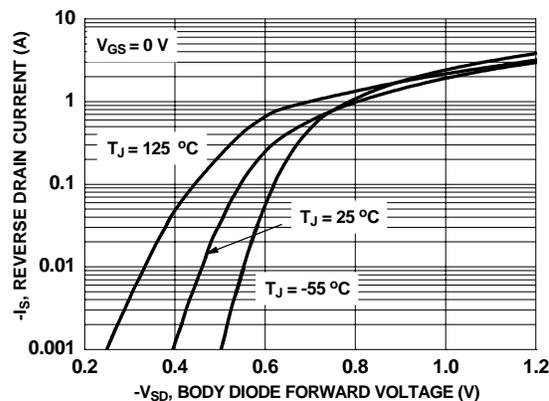


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted

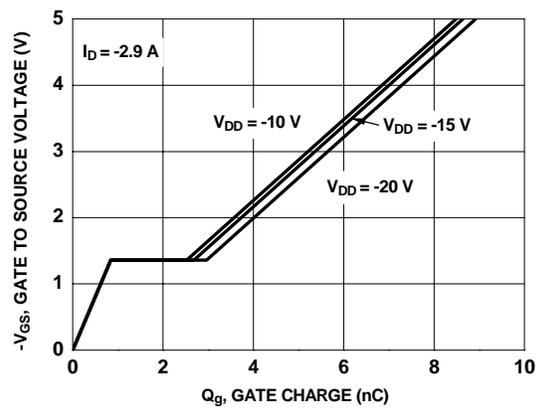


Figure 7. Gate Charge Characteristics

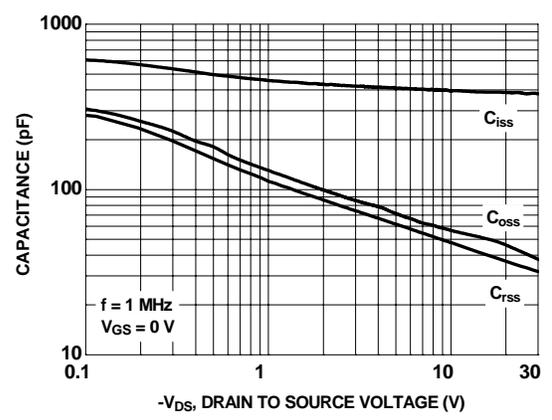


Figure 8. Capacitance vs Drain to Source Voltage

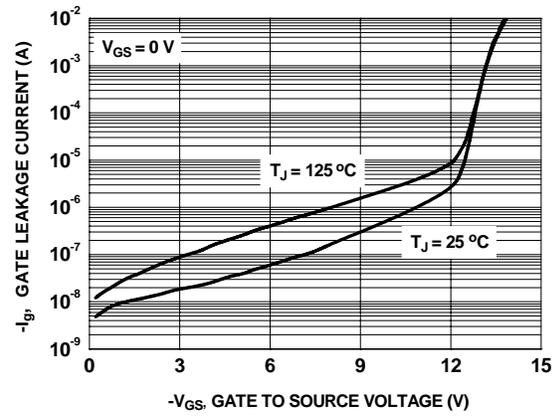


Figure 9. Gate Leakage vs Gate to Source Voltage

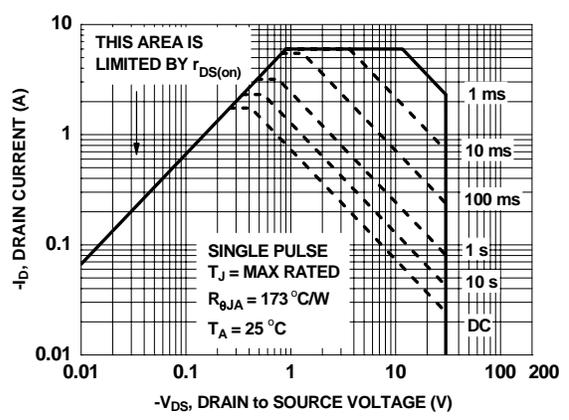


Figure 10. Forward Bias Safe Operating Area

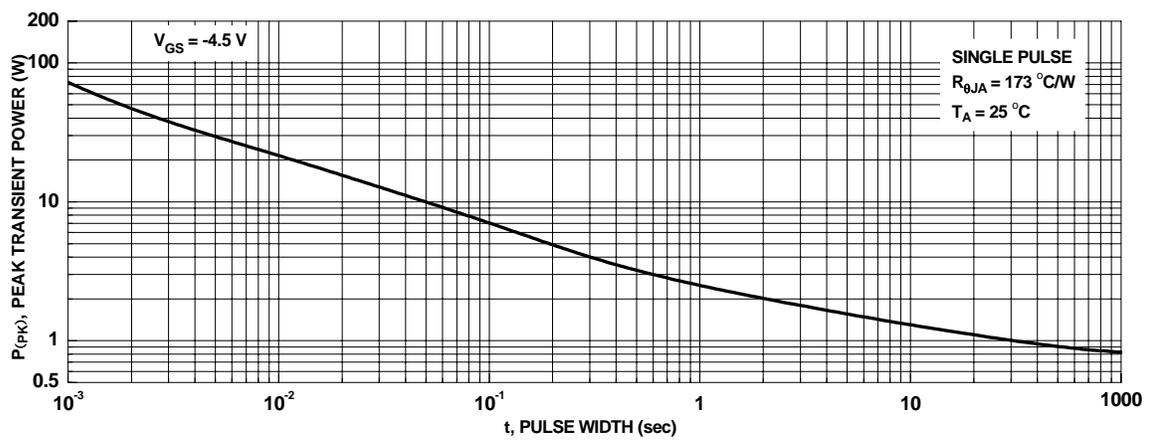


Figure 11. Single Pulse Maximum Power Dissipation

Typical Characteristics $T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted

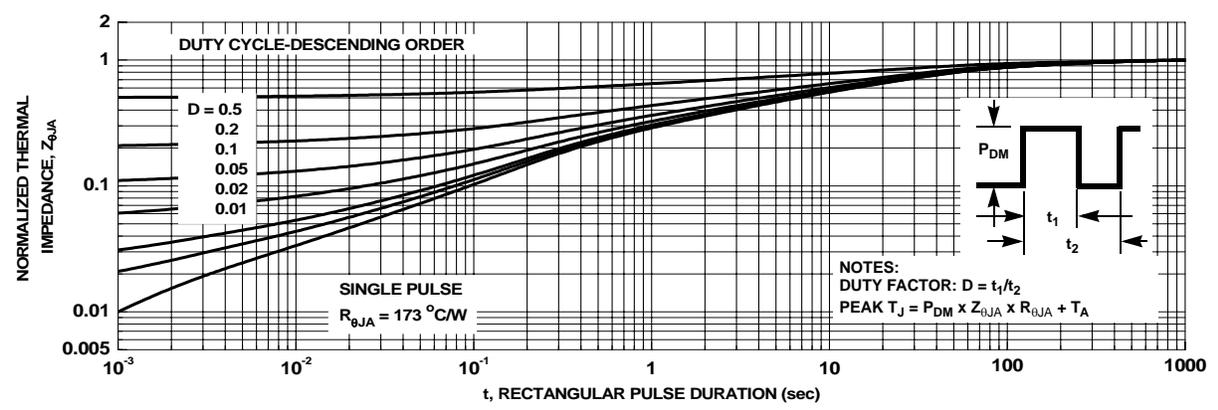
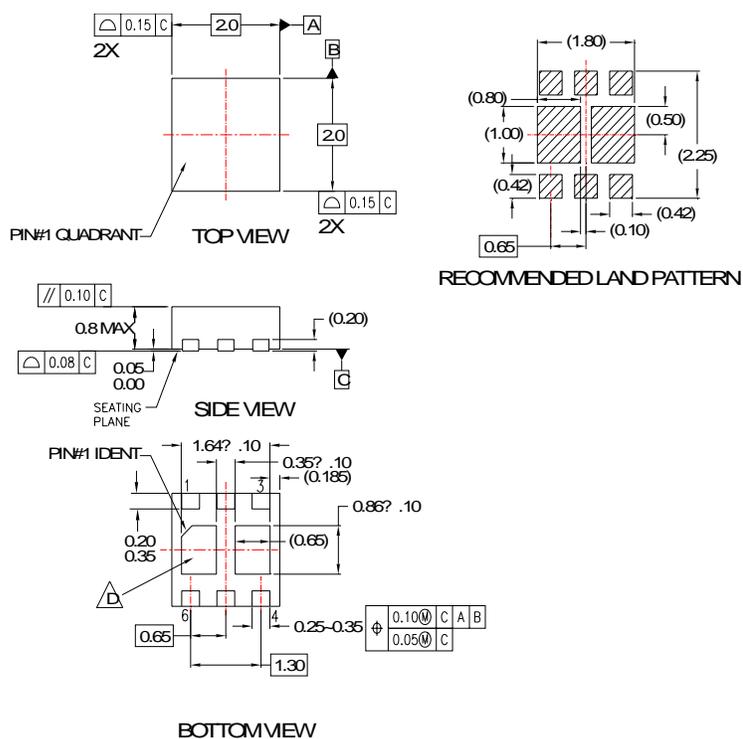


Figure 12. Junction-to-Ambient Transient Thermal Response Curve

Dimensional Outline and Pad Layout



NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-229, VARIATION VOCC EXCEPT AS NOTED.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994
- \triangle D. NON-JEDEC DUAL DAP

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